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<b>FORM PTO 1449 US Department of Commerce</b> <b>Patent and Trademark Office</b>		Application Number	10/063,049		
		Filing Date	March 14, 2002		
		First Named Inventor	Ryza et al.		
		Group Art Unit	4723 / 756		
		Examiner Name	Unknown DUDA		
Sheet	1	of	2	Attorney Docket Number	TEX1100

## U.S. PATENT DOCUMENTS

Examiner Initials	Cite No.	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		Number	Kind Code (if known)		
ICAD	A1	5013366	134/1	05/07/91	Jackson et al.
ICAD	A2	6277753	438/692	08/21/01	Mullee et al.
ICAD	A3	6331487	438/692	12/18/01	Koch
ICAD	A4	20010008800		07/19/01	Koch
ICAD	A5	6306564	430/329	10/23/01	Mullee
ICAD	A6	6224774	210/634	05/01/01	DeSimone et al.
ICAD	A7	5377705	134/953	01/03/95	Smith, et al.
ICAD	A8	5944996	210/634	08/31/99	DeSimone et al.
ICAD	A9	6067728	34/470	05/30/00	Farmer et al.
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ICAD	A12	6225995	345/335	05/01/01	Jacobs et al.
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Examiner Signature		K. Duda		Date Considered	12-8-03



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**FOREIGN PATENT DOCUMENT**

Examiner Initials	Cite No.	Country Code	Number	Kind Code (if known)	Publication Date MM-DD-YYYY (Number 43)	Name of Patentee or Applicant of Cited Document
KAD	B1	PCT	WO 01/33613	A2	05/10/01	Supercritical Systems, Inc.
KAD	B2	PCT	WO 02/15251	A1	08/14/00	Tokyo Electron Limited
KAD	B3	EP	0 397 826	B1	12/16/92	Hughes Aircraft Company
	B4	JP	60 192333	A	9/30/85	Hitachi Seisakusho

**OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS**

Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	Date
KAD	C1	KING, et al., "The Mutual Solubilities of Water with Supercritical and Liquid Carbon Dioxide", The Journal of Supercritical Fluids, Volume 5, pages 296-302.	May 1992
KAD	C2	PERRY, et al., "Chemical Engineers' Handbook", 5th Edition, pp. 21-11 to 21-14 (4 sheets).	1973
KAD	C3	Phase Diagram for CO <sub>2</sub> as found at <a href="http://www.chem.uncc.edu/faculty/murphy/1252/Chapter11B/sldoo4.htm">http://www.chem.uncc.edu/faculty/murphy/1252/Chapter11B/sldoo4.htm</a>	February 7, 2002
KAD	C4	Bruan, et al., "Photostrip faces 300 mm, copper and low-k convergence," 7 pages, Semiconductor International.	September 2000
KAD	C5	Sundararajan, et al., "Block copolymers as supercritical CO <sub>2</sub> developable photoresists" Department of Materials Science and Engineering, pp. 130-131.	-
KAD	C6	Rubin, et al., "A Comparison of Chilled DI Water/Ozone and CO <sub>2</sub> -Based Supercritical Fluids as Replacements for Photoresist-Stripping Solvents," International Electronics Manufacturing Technology Symposium, pp. 308-314.	January 1998
KAD	C7	Gabor, et al., "Block and Random Copolymer Resist Designed for 193 nm Lithography and Environmentally Friendly Supercritical CO <sub>2</sub> Development," SPIE Vol. 2724, pp. 410-417.	June 1996
KAD	C8	Wetmore, et al., "Supercritical Fluid Processing: A New Dry Technique for Photoresist Developing," SPIE Vol. 2438, pp. 694-703.	June 1995
Examiner Signature		K. Duda	Date Considered 12-8-03

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